

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-2. (cancelled)

3. (currently amended) A production process of light emitting device equipped with a substrate, light emitting layers formed on the substrate, and an insulator layer mutually partitioning the light emitting layers;

wherein the production process includes a process of forming the insulator layer by a thermal transfer method to produce the light emitting device equipped with the substrate, the light emitting layers formed on the substrate, and the formed insulator layer mutually partitioning the light emitting layers.

4. (original) A production process of a light emitting device according to claim 3, which includes;

a process of forming the insulator layer on a transfer member by a thermal transfer method, and

a process of transferring the insulator layer which has been formed on the transfer member, to the substrate.

5-6. (cancelled)

7. (original) A production process of a light emitting device according to claim 3;

wherein the light emitting layers contain a light emitting material emitting light by impressing electric field.

8. (original) A production process of a light emitting device according to claim 4;

wherein the light emitting layers contain a light emitting material emitting light by impressing electric field.

9-10. (cancelled)

11. (original) A production process of a light emitting device according to claim 3;

wherein the substrate is composed of a resin.

12. (original) A production process of a light emitting device according to claim 4;

wherein the substrate is composed of a resin.

13-14. (cancelled)

15. (original) A production process of a light emitting device according to claim 7;

wherein the substrate is composed of a resin.

16. (original) A production process of a light emitting device according to claim 8;

wherein the substrate is composed of a resin.

17. (new) A process for producing a light emitting device, comprising the step of:

using a thermal transfer method to form an insulator layer mutually partitioning light emitting layers of a light emitting device, wherein,

the light emitting device is produced with a substrate, the light emitting layers formed on the substrate, and the formed insulator layer mutually partitioning the light emitting layers.

18. (new) The process for producing an electroluminescence panel of claim 17, comprising the further steps of:

forming an electroluminescence panel substrate composed of a transparent film with a plural number of first electrodes extended on the substrate in a stripe shape to left and right directions; and

forming a plural number of second electrodes in a stripe shape to a direction orthogonalized against the first electrodes at a position duplicated with the light emitting layers.

19. (new) The process for producing an electroluminescence panel of claim 17,

comprising the further step of providing an electroluminescence panel substrate, and

wherein the thermal transfer method step comprises providing i) a ribbon composed of a base film and a transfer layer coated on a surface of the base film, ii) conveying the ribbon and the substrate between a thermal head and a platen roll so that selected portions of the transfer layer are transferred onto the substrate to form the insulator layer.

20. (new) The process for producing an electroluminescence panel of claim 19, wherein,

the thermal head is equipped with a plural number of heating members arranged to a direction orthogonalized to a conveying direction of the substrate, and

a portion of the transfer layer is selectively melted and transferred onto the substrate by impressing signals to the respective heating members while conveying the substrate.

21. (new) The process of claim 17, wherein the substrate is composed of a polymer film.

22. (new) The process of claim 17, wherein the substrate is composed of an inorganic material.

23. (new) The process of claim 19, wherein,
conveying the ribbon and the substrate between the thermal head and the platen roll, so that the transfer layer is transferred onto the substrate to form the insulator layer, includes an indirect transfer of the selected portions of the transfer layer onto the substrate, and

the indirect transfer is by first transferring the selected portions of the transfer layer onto an elastic intermediate transfer roll and then from the transfer roll onto the substrate.

24. (new) The process of claim 23, wherein,
the substrate is inelastic.